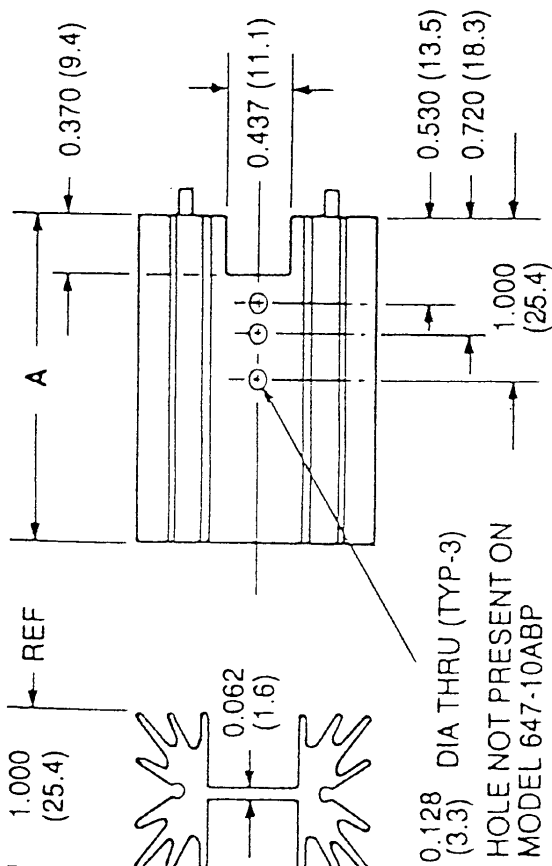
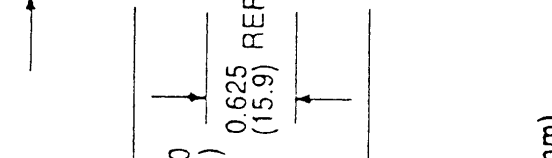


647 SERIES
(EXTRUSION PROFILE 5195)



647 SERIES
HOLE NOT PRESENT ON
MODEL 647-10ABP



647 SERIES
HOLE NOT PRESENT ON
MODEL 647-10ABP

TO-220

| Thermal Performance at Typical Load | | Weight |
|-------------------------------------|-----------|---------------|
| Natural Convection | 42°C @ 6W | lbs (grams) |
| Forced Convection | 37°C @ 6W | 0.055 (24.95) |
| | 34°C @ 6W | 0.075 (34.02) |
| | 31°C @ 6W | 0.090 (40.82) |
| | 25°C @ 6W | 0.104 (47.17) |
| | | 0.125 (56.70) |

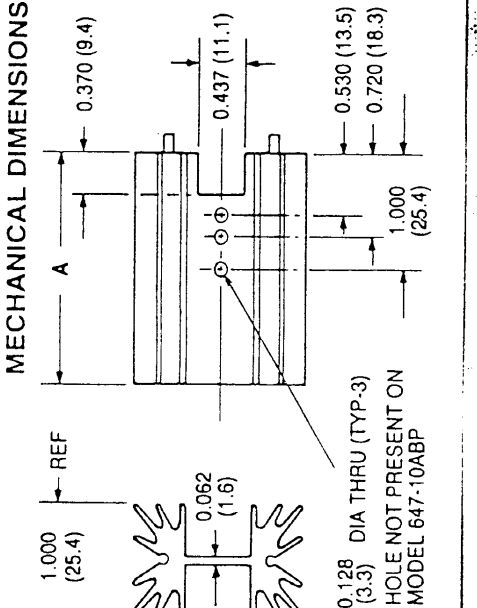
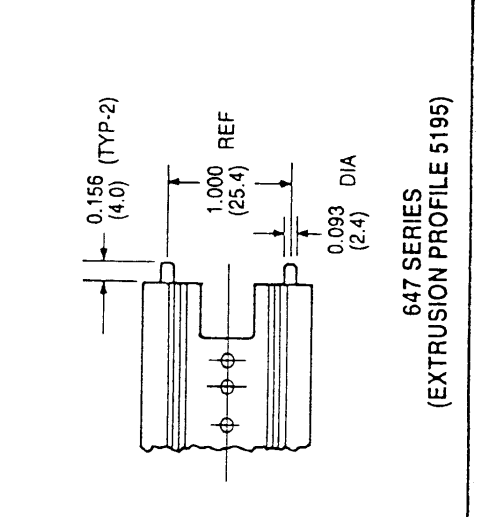
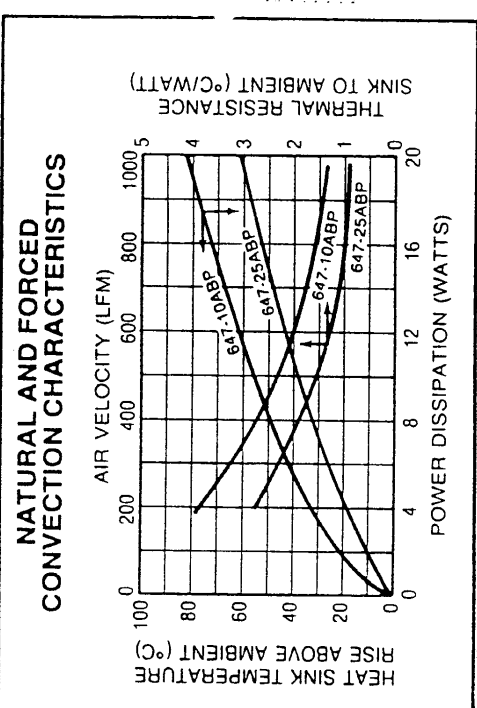
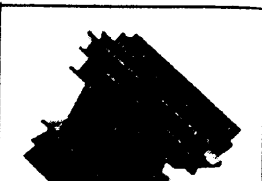
High-Performance Heat Sinks for Vertical Board Mounting

Maximum Footprint
 1.650 in. (41.9) x 1.000 (25.4)
 1.650 in. (41.9) x 1.000 (25.4)
 1.650 in. (41.9) x 1.000 (25.4)
 1.650 in. (41.9) x 1.000 (25.4)
 1.650 in. (41.9) x 1.000 (25.4)

647 SERIES

Standard P/N
 647-10ABP ▲
 647-15ABP ▲
 647-175ABP ▲
 647-20ABP ▲
 647-25ABP ▲

Wave-solderable pins on 1 in. centers for vertical mounting of larger devices on printed circuit boards. Maximum semiconductor package width: 0.625 (15.9). Refer to the Accessory Products section for thermal interface materials, 126 Series silicone-free thermal compounds, and other accessories products. Material: aluminum, black anodized.



647 SERIES
(EXTRUSION PROFILE 5195)

s: in. (mm)